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TECHNICAL

INSTRUCTIONS

DATA SHEETS

NEUTRONEX NT 2000 HS

High Speed Pure gold Electroplate For Electronic Components

INTRODUCTION

NEUTRONEX NT 2000 HS gold plating process is a newly developed High Speed formulated specially to produce a high purity gold deposit (99.99%) having excellent physical properties. Deposits produce by this process are smooth, lustrous, highly ductile and free from porosity. The process particularly useful for bonding operations and where exceptional solderability is required.

NEUTRONEX NT 2000 HS maintains this high purity level consistently under practical electroplating control procedures, and produces stress-free deposit up to any desirable thickness making them ideal for those electronic applications (ie. Printed Circuit Board. Semi-Conductor and connector industries). Suitable for both rack and high speed selective plater no special conditions are required and the process is simple to operate.

NEUTRONEX NT 2000 HS produce deposits which conform to MIL-G-45204B, class 00 to class 6, Types 1,2,3, Grade B.

PROCESS FEATURES

- * Ultra-pure gold deposit (99.99%)
- * Excellent bonding characteristics
- * Stress free, low porosity
- * Uniform distribution
- * Exceptional throwing power
- * Easy to operate
- * High coating thickness
- * Extreme higher plating speed and wide operating window

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CHEMICALS CORPORATION

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DEPOSIT CHARACTERISTICS

Appearance	Semi to mirror bright
Purity	99.99%
Hardness	60 – 70 mHV20
Specific Gravity (± 0.1)	19.0

Contact resistivity	0.3 milliohms (using the cross wire method with a 200 gram load)
Porosity	Relatively pore free deposits are obtained at thickness of 1-1.25 microns

EQUIPMENT REQUIRED

Tank	Polypropylene or PVC glass fibre reinforced tank are suitable.
Heater	Heating is required and temperature regulation is essential. Therefore, thermostatically